# 2SD0966 (2SD966)

## Silicon NPN epitaxial planer type

For low-frequency power amplification For stroboscope

## Features

• Low collector to emitter saturation voltage V<sub>CE(sat)</sub>.

Absolute Maximum Ratings (Ta=25°C)

• Satisfactory operation performances at high efficiency with the low-voltage power supply.

Parameter	Symbol	Ratings	Unit			
Collector to base voltage	V <sub>CBO</sub>	40	V			
Collector to emitter voltage	V <sub>CEO</sub>	20	V			
Emitter to base voltage	V <sub>EBO</sub>	7	V			
Peak collector current	I <sub>CP</sub>	8	А			
Collector current	I <sub>C</sub>	5	А			
Collector power dissipation	P <sub>C</sub>	1	W			
Junction temperature	Tj	150	°C			
Storage temperature	T <sub>stg</sub>	-55 ~ +150	°C			

# Unit: mm $\begin{array}{c} 5.9\pm0.2 \\ \hline 0.7\pm0.1 \\ 0.45^{+0.2} \\ 0.45^{+0.2} \\ 1.27 \\ 1.27 \\ 1.23 \\ 2.54\pm0.15 \\ 2.54\pm0.15 \\ 2.50lector \\ 3:Base \\ EIAJ:SC-51 \\ TO-92L-A1 Package$

### Electrical Characteristics (Ta=25°C)

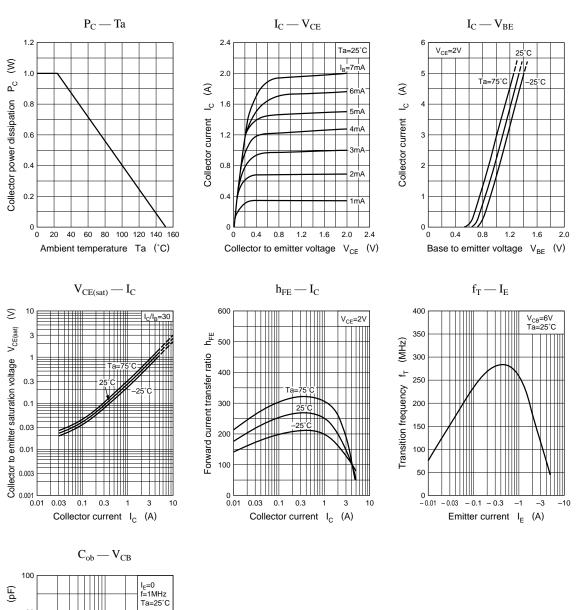
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = 10V, I_E = 0$			0.1	μΑ
Emitter cutoff current	I <sub>EBO</sub>	$V_{EB} = 7V, I_{C} = 0$			0.1	μΑ
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = 1 \mathrm{mA},  I_{\rm B} = 0$	20			v
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	7			v
<b>T</b>	h <sub>FE1</sub> *1	$V_{CE} = 2V, I_C = 0.5A^{*2}$	230		600	
Forward current transfer ratio	h <sub>FE2</sub>	$V_{CE} = 2V, I_C = 2A^{*2}$	150			
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 3A, I_{\rm B} = 0.1A^{*2}$			1	v
Transition frequency	f <sub>T</sub>	$V_{CB} = 6V, I_E = -50mA, f = 200MHz$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 20V, I_E = 0, f = 1MHz$			50	pF

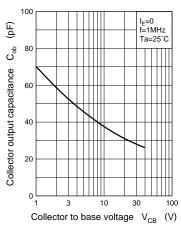
\*2 Pulse measurement

\*1hFE1 Rank classification

Rank	Q	R
h <sub>FE1</sub>	230 ~ 380	340 ~ 600

Note.) The Part number in the Parenthesis shows conventional part number.





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